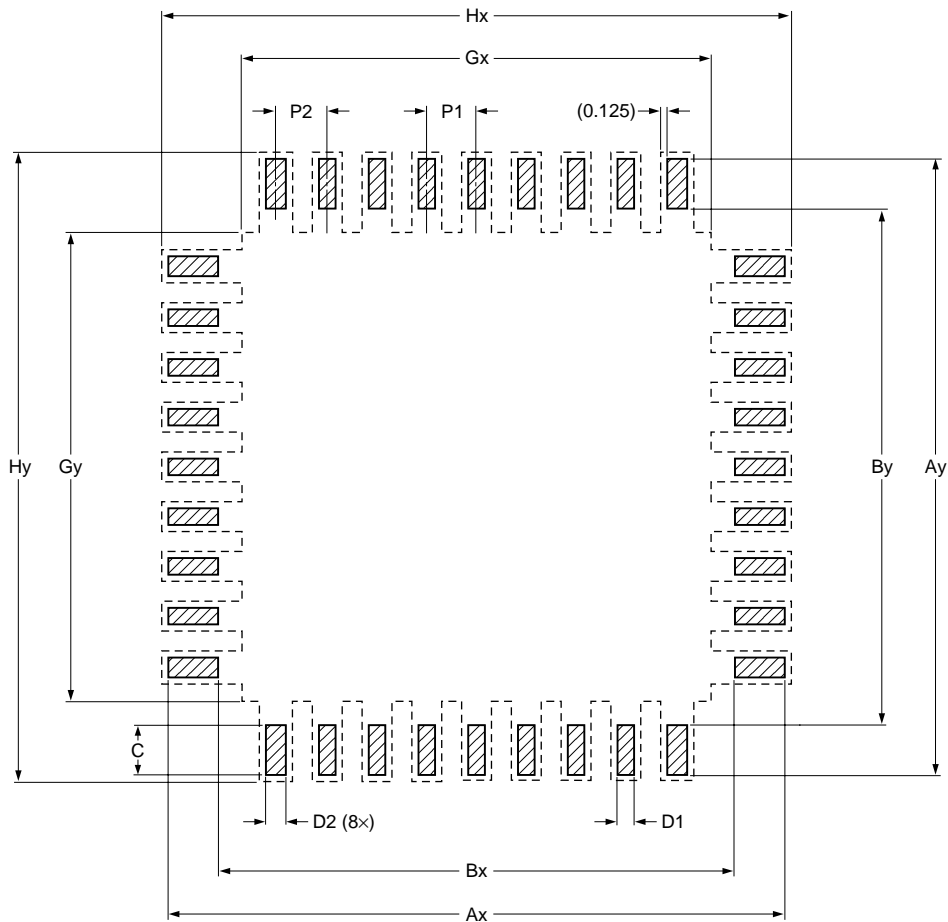


Footprint information for reflow soldering of QFP52 package

SOT379-2



Generic footprint pattern
Refer to the package outline drawing for actual layout

- solder land
- occupied area

DIMENSIONS in mm

| P1 | P2 | Ax | Ay | Bx | By | C | D1 | D2 | Gx | Gy | Hx | Hy |
|-------|-------|--------|--------|--------|--------|-------|-------|-------|--------|--------|--------|--------|
| 0.650 | 0.700 | 13.900 | 13.900 | 10.900 | 10.900 | 1.500 | 0.400 | 0.500 | 10.500 | 10.500 | 14.150 | 14.150 |